Product End-of-Life Disassembly Instructions

Product Category: *Networking*
Marketing Name / Model [List multiple models if applicable.]
HPE Aruba USB LTE Modem

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

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Item Description	Notes	Quantity of items included in product
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screwdriver	T6
Torx screwdriver	T9
Static electric tweezer	NA
Phillips screwdriver	PH1

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Using Torx screwdriver remove screw on bottom side, remove cover plate of SIM slot (Type T6).
2. Use tweezer to remove two rubber foot pads on the bottom side.
3. Using Torx screwdriver remove two screws on bottom side underneath the rubber food pad (Type T9).
4. Open top cover from USB Connector side.
5. Using Phillips screwdriver to remove screw of metal shielding then remove metal shielding (Type PH1).
6. Remove thermal pad on top of main PCB.
7. Remove three Antenna wire connectors and one wire connector from USB connector to PCBA.
8. Remove PCBA from cover and use Phillips's screwdriver to remove screw of the module PCBA to remove it from main PCBA (Type PH1).
9. Remove thermal pad and conductive foam between main and module PCBA.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

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1. Using Torx screwdriver remove screw on bottom side, remove cover plate of SIM slot (Type T6).





2. Use tweezer to remove two rubber foot pads on the bottom side.



3. Using Torx screwdriver remove two screws on bottom side underneath the rubber food pads (Type T9).



4. Open top cover from USB Connector side.





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5. Using Phillips screwdriver to remove screw of metal shielding then remove metal shielding (Type PH1).



6. Remove the thermal pad on top of main PCB.





7. Remove three Antenna wire connectors and one wire connector from USB connector to PCBA.





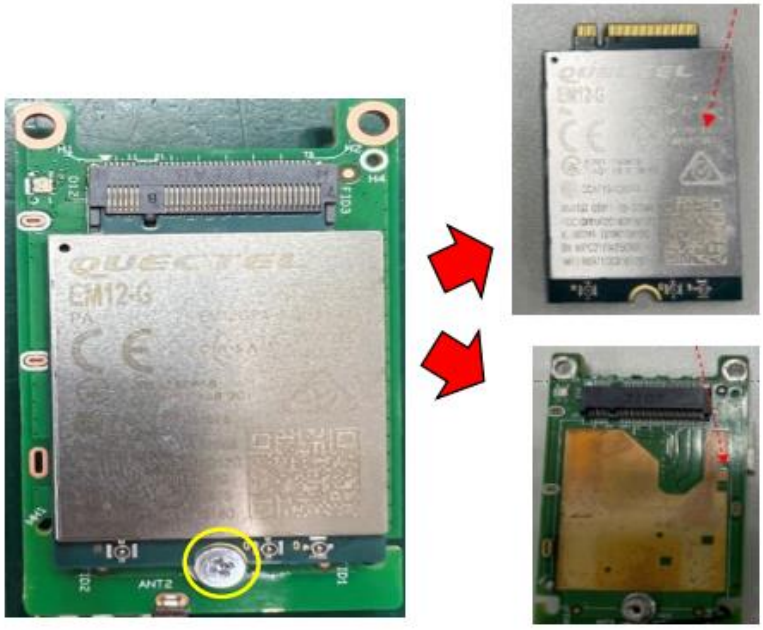




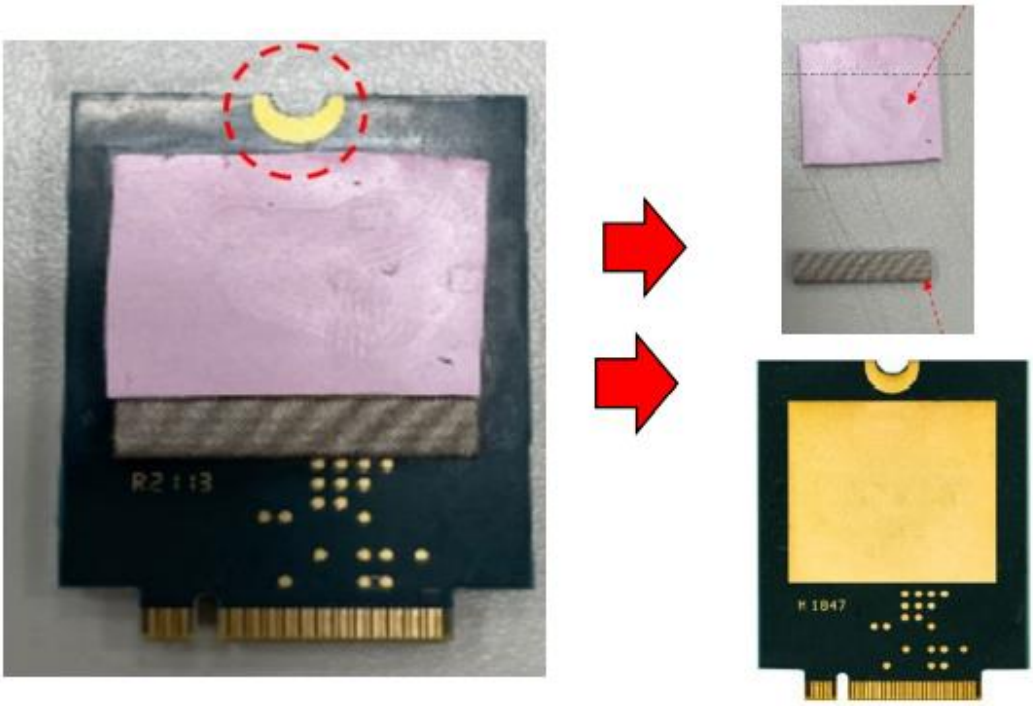
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8. Remove PCBA from cover and use Phillips's screwdriver to remove screw of the module PCBA to remove it from main PCBA (Type PH1).



9. Remove thermal pad and conductive foam between main and module PCBA.



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